

This information is derived from development samples
made available for evaluation. It does not necessarily
apply that the device will go into regular production.

SOLDERING

1. By hand

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C it must not be in contact for more than 10 seconds; if between 300 °C and 400 °C, for not more than 5 seconds.

2. By dip or wave

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds. The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

3. Repairing soldered joints

The same precautions and limits apply as in (1) above.

MICROCOMPUTER/MICROPROCESSOR PERIPHERAL

IC FOR VIEWDATA (LUCY)

The SAA5070 is a complex microcomputer/microprocessor peripheral integrated circuit in N-channel MOS technology intended for use in wired data communication systems, notably viewdata.

Features

- Microcomputer/microprocessor interface.
- Modem — both 1200/75 and 1200/1200 baud.
- Line "UART" and tape recorder "UART", both with software parity control (or 8-bit without parity).
- Tape recorder modem (modified 'Kansas City' standard 1300 baud).
- Autodialler for British Post Office and Continental requirements.
- IBUS receivers and transmitters.
- Timer circuits (60 s and 1.5 s time-outs).
- General input/output ports.
- Provision for connection of any external modem through V24 interface.

QUICK REFERENCE DATA

Supply voltage	V _{DD}	nom.	5	V
Supply current	I _{DD}	typ.	75	mA
Operating ambient temperature range	T _{amb}	-20 to +70	°C	

purple binder, tab 6

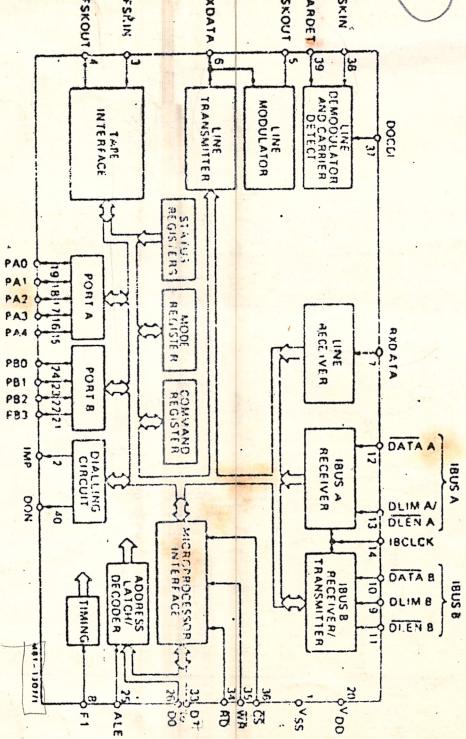


Fig.1a Simplified block diagram

PACKAGE OUTLINE

40-lead DIL; plastic (SOT-129).

40-LEAD DUAL IN-LINE; PLASTIC (SOT-129)

See next page

SOLDERING

Dimensions in mm

(3) Index may be horizontal as shown.

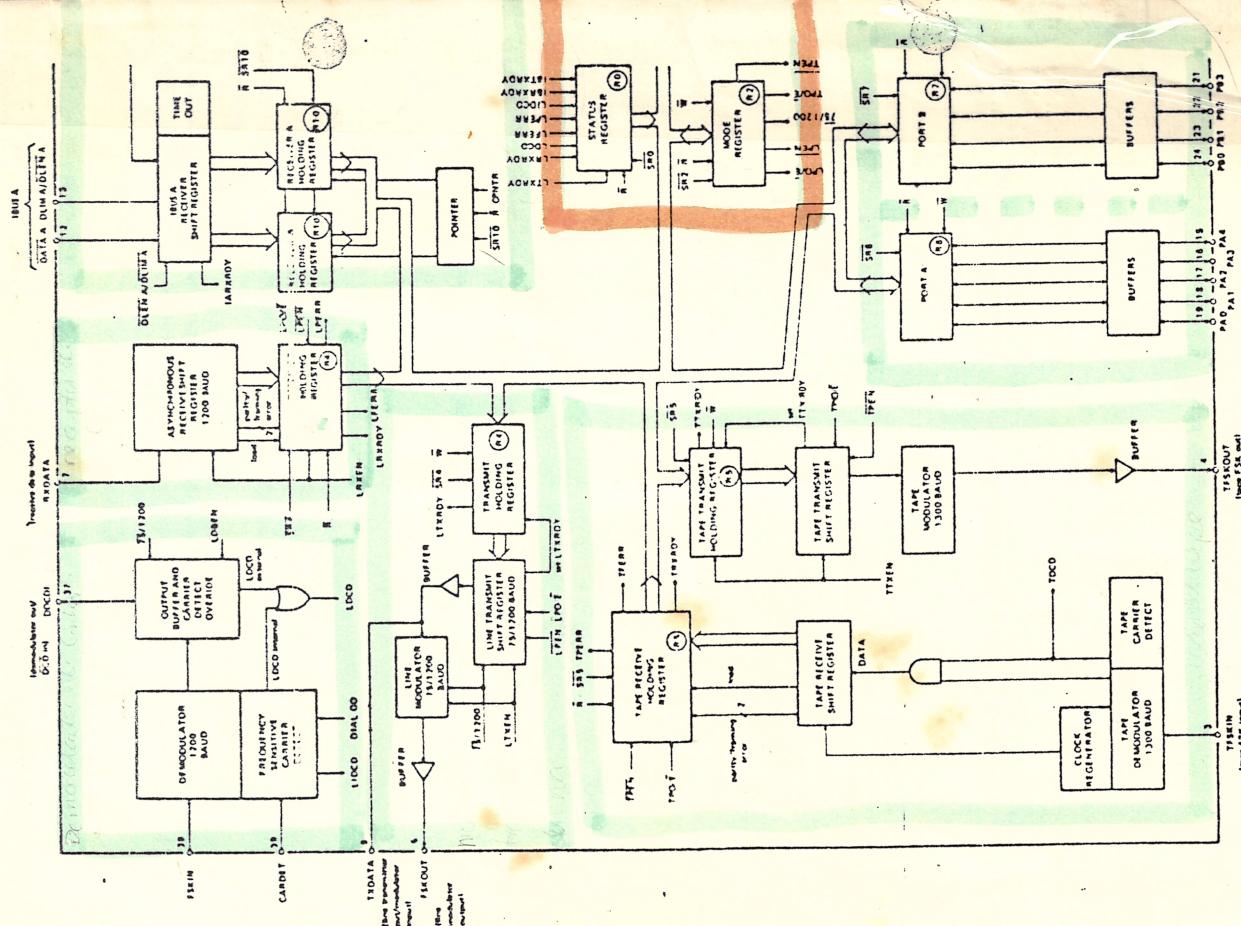
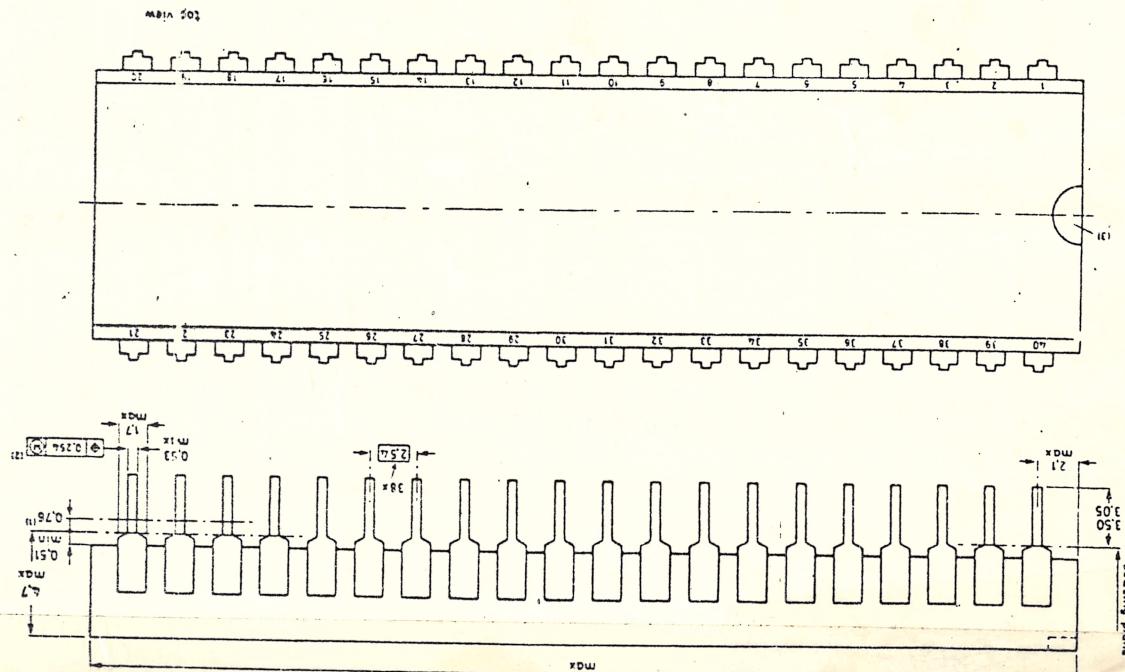
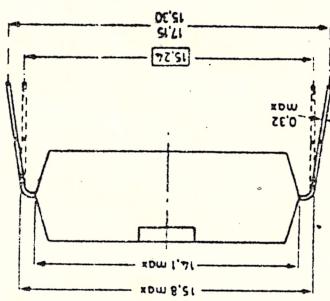
[2] Lead spacing tolerances apply from setting planes to the line indicated.

Centre-lines of all leads are within ±0.127 mm of the nominal position shown; in the worst case, the spacing between any two leads may deviate from nominal by ±0.254 mm.

(M) Maximum Material Condition.

W W

Positional accuracy.



MEMORIC LIST

<u>ALE</u>	address latch enable from microprocessor
<u>CLOCK IN/OUT</u>	input/output control for 62.5 kHz clock pin
<u>CPNTR</u>	pointer signal for two byte registers
<u>DLEN A/D/LIMA</u>	three line/two line control for IBUS A receiver
<u>DON</u>	dial off normal relay control for dialling
<u>IMP</u>	impulsing relay control for dialling
<u>IARXRDY</u>	IBUS A receiver ready — data available
<u>IBXRDX</u>	IBUS B receiver ready — data available
<u>IBTXRDY</u>	IBUS B transmitter ready — previous transmission complete
<u>LDBEN</u>	line demodulator output buffer enable
<u>LDCD</u>	line data carrier detected
<u>LFERR</u>	line receiver framing error — received stop bit not HIGH
<u>LIDCD</u>	line instantaneous data carrier detect
<u>UPEN</u>	line parity enable command
<u>LPERR</u>	line receiver parity error flag
<u>LPO/E</u>	line parity odd/even command
<u>LRXEN</u>	line receiver enable
<u>LRXRDY</u>	line receiver ready — data available
<u>LTXEN</u>	line transmitter and modulator enable
<u>LTXRDY</u>	line transmitter ready — transmit holding register empty
<u>SRn</u>	select register 'n'
<u>TDCC</u>	tape data carrier detected
<u>TFERR</u>	tape receiver framing error — received stop bit not HIGH
<u>TPEN</u>	tape parity enable command
<u>TRERR</u>	tape receiver parity error flag
<u>TPO/E</u>	tape parity odd/even command
<u>TRXEN</u>	tape receiver enable
<u>TRXRDY</u>	tape receiver ready — data available
<u>TTXEN</u>	tape transmitter enable
<u>TTXRDY</u>	tape transmitter ready — transmit holding register empty
<u>UK/EUR</u>	impulsing ratio control for UK and European standards
<u>75/1200</u>	baud rate selection command for line modulator and line transmit shift register

DEVELOPMENT SAMPLE DATA

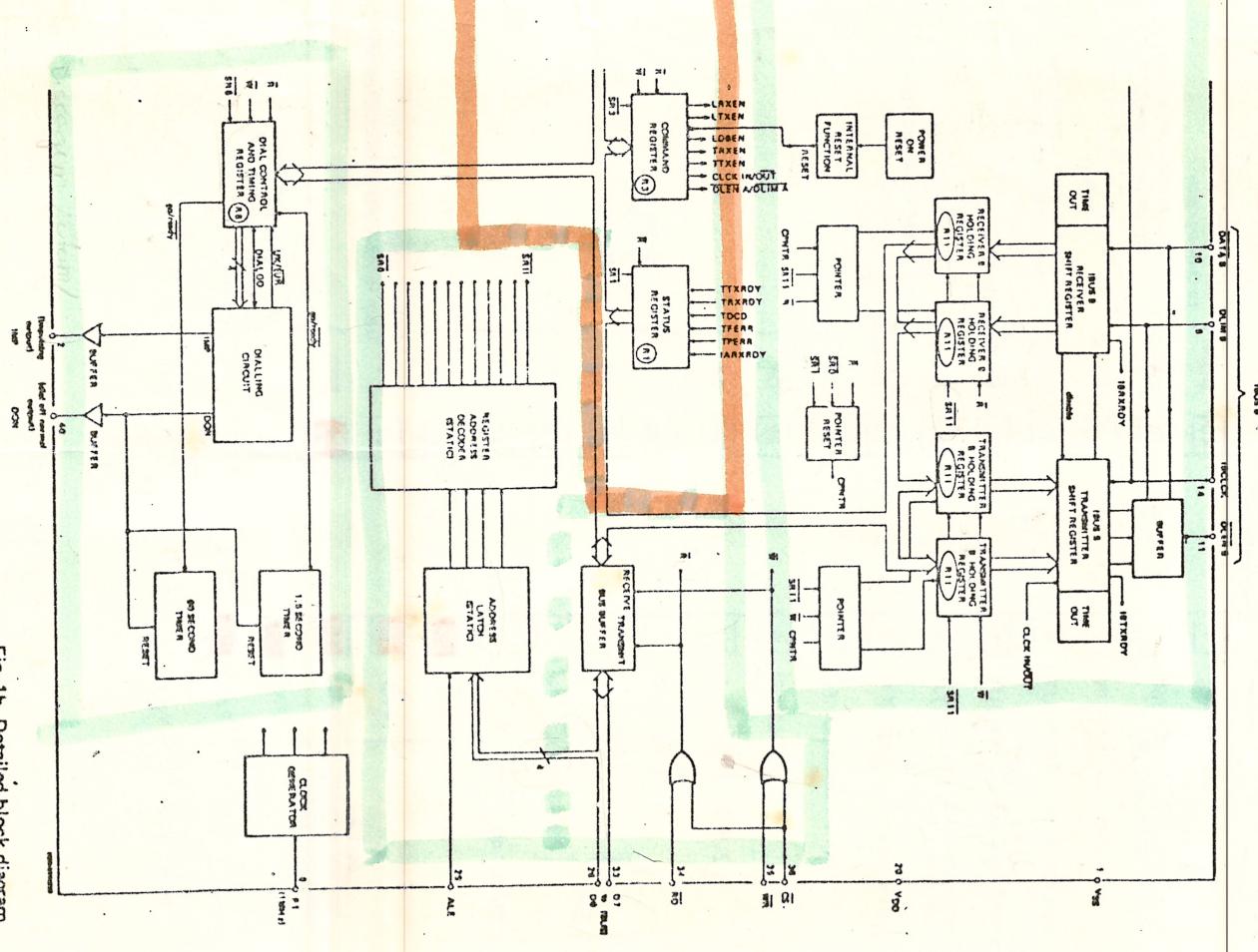


Fig. 1b. Detailed block diagram

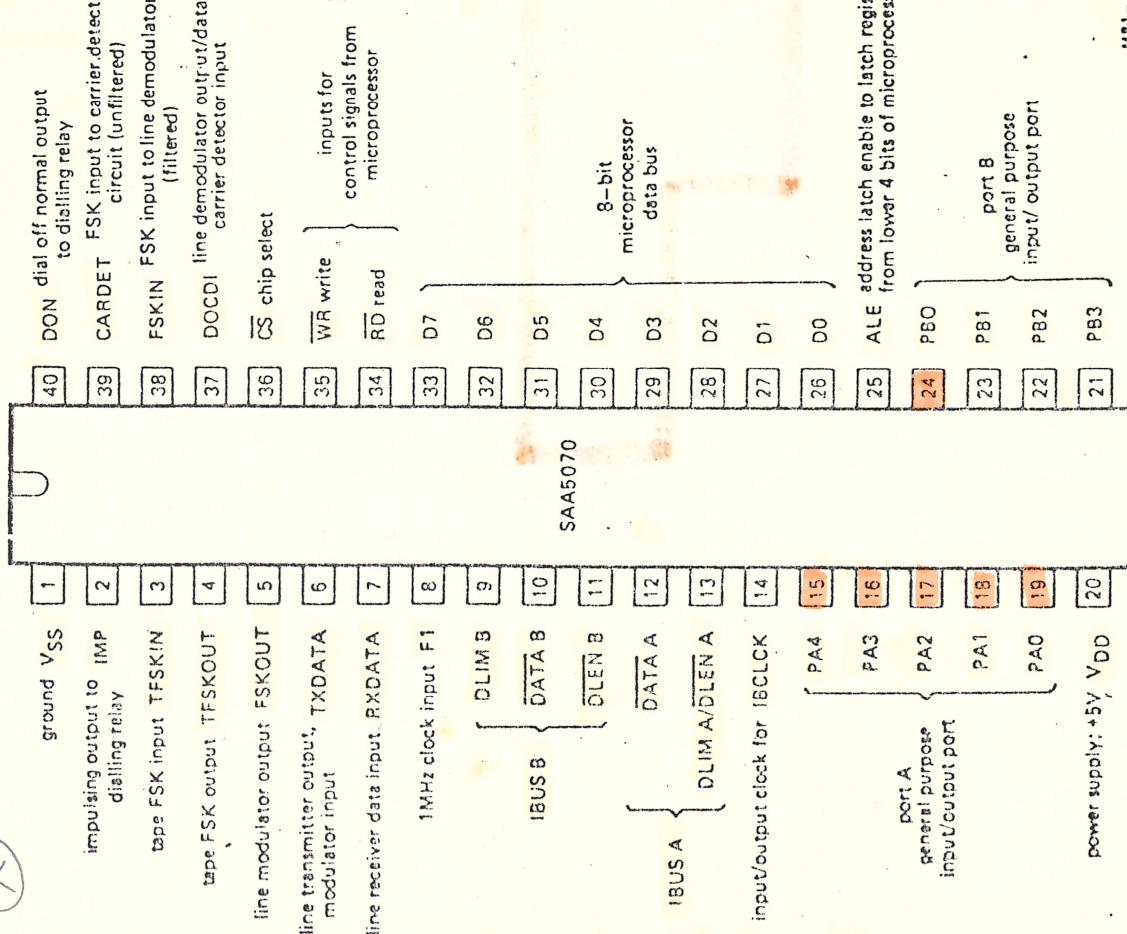


Fig.2 Pinning diagram

For details of bit movement in R10 and R11 see discussion of IBUS operation. A mnemonic list for use with this register map and Fig.1b is given on the next page.

NOTE R9 is unused.

Register map (continued)

APPENDIX

DEVELOPMENT SAMPLE DATA

APPENDIX
Register map

	D7	D8	D5	D4	D3	D2	D1	DO-	
R0	LTXRDY R	LRXRDY R	LDCD R	LFERR R	LPERR R	LIDCD R	IBRXRDY R	IBTXRDY R	STATUS REGISTER 0
R1	TTXRDY R	TRXRDY R	TOCD R	TFERR R	TPERR R		JARXRDY R		STATUS REGISTER 1
R2	LPO/E R/W	LPEN R/W	75/1200 R/W		TPO/E R/W	TPEN R/W			MODE REGISTER
R3	LRXEN R/W	LTXEN R/W	RESET R/W	LOBEN R/W	TRXEN R/W	TTXEN R/W	CLOCK IN/OUT R/W	DLEN A/D/LIM A R/W	COMMAND REGISTER
R4	PARITY OR B8 (R)	B7 R	B8 R	B5 R	B4 R	B3 R	B2 R	B1 R	LINE RECEIVE HOLDING REGISTER
R4	PARITY OR B8 (W)	B7 W	B8 W	B5 W	B4 W	B3 W	B2 W	B1 W	LINE TRANSMIT HOLDING REGISTER
R5	PARITY OR B8 (R)	B7 R	B8 R	B5 R	B4 R	B3 R	B2 R	B1 R	TAPE RECEIVE HOLDING REGISTER
R5	PARITY OR B8 (W)	B7 W	B8 W	B5 W	B4 W	B3 W	B2 W	B1 W	TAPE TRANSMIT HOLDING REGISTER
R6				PA4 R/W	PA3 R/W	PA2 R/W	PA1 R/W	PA0 R/W	PORT A
R7					PB3 R/W	PB2 R/W	PB1 R/W	PB0 R/W	PORT B
R8	UK/EUR R/W	60s TIMER R/W	DIAL GO R/W	1.6s TIMER R/W	D13	D12	D11	D10	DIAL CONTROL AND TIMING REGISTER
R10A	B8 R	B7 R	B8 R	B5 R	B4 R	B3 R	B2 R	B1 R	IBUS A REGISTERS
R10B	WL3 R	WL2 R	WL1 R	WL0 R	B12 R	B11 R	B10 R	B9 R	

DEVELOPMENT SAMPLE DATA

RATINGS Limiting values in accordance with the Absolute Maximum System (IEC134).

Voltages (with respect to pin 1)
Supply voltage (pin 20)

Input voltage:

PORT A (pins 15 to 19) and PB0 (pin 24)

Input voltage (all other pins)

Temperatures

Storage temperature range

Operating ambient temperature range

Supply voltage (pin 20)

V_I	-0.3	-14.0 V
V_I	-0.3	7.5 V
T_{stg}	-20 to $+125$ °C	
T_{amb}	-20 to $+70$ °C	

The following characteristics apply at $T_{amb} = 25$ °C and $V_{DD} = 5$ V unless otherwise stated.

Supply current	I_{DD}	—	75	150	mA
Inputs					
All inputs (except F1 clock)					
Input voltage; LOW	V_{IL}	-0.3	—	0.8	V
Input voltage; HIGH	V_{IH}	2.0	—	5.5	V
Input leakage current ($V_I = 0$ to 5.5 V)	I_{IR}	—	—	10	μA
Input capacitance	C_I	—	—	7	pF

The SAA5070 is a 40 pin integrated circuit in N-channel MOS with a 1 MHz clock supplying all the operating frequencies. It performs most of the hardware functions of a videotext terminal including an autodialling circuit, a 1200 baud demodulator and asynchronous receiver, and a 75/1200 baud modulator and asynchronous transmitter.

The device also includes a tape interface circuit suitable for the recording of character codes of pages of text on a standard audio cassette recorder, and an IBUS receiver and receiver/transmitter on separate ports enabling the software recording of IBUS transmissions. The 75 baud modulator and asynchronous transmitter can be switched to operate at 1200 baud for private telecommunications systems. There are also two general purpose input/output ports, Port A could, for example, be used as an interface to a non volatile RAM which can store telephone numbers for autodialling and user passwords and Port B could be used for display control.

The SAA5070 has been partitioned for flexibility of use, e.g. an external modem can be used independently of, and simultaneously with, the line receiver.

HANDLING

Inputs and outputs are protected against electrostatic charge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices. (See 'HANDLING MOS DEVICES').

Data specific to certain inputs

F1 (1 MHz) Clock	min.	typ.	max.	
Input voltage; LOW	-0.3	-	0.6	V
Input voltage; HIGH	2.2	-	5.5	V
Input leakage current ($V_I = 0$ to 5.5 V)	I_{IH}	-	10	μA
Input capacitance	I_{IR}	-	7	pF
Mark/space ratio (measured at 1.5 V level)	C_1	40:60	-	60:40
<u>DATA A, DLIM A/DLEN A (IBUS A)</u>				
Data set up time	t_{DS}	3	-	μs
Data hold time	t_{DH}	3	-	μs
DLIM clock; HIGH	t_{CH}	4	-	μs
DLIM clock; LOW	t_{CL}	4	-	μs
Time between commands	t_{BC}	140	-	∞ μs
DLIM frequency	f_{DLIM}	16	-	160 kHz

ALE (Address Latch Enable) (Figs. 3 and 4)

Pulse width (HIGH)

Cycle time

 \overline{RD} , \overline{WR} and \overline{CS} (Figs. 3 and 4)

Control pulse width

Address hold time

Address setup time

Read cycle timings (Fig. 3)

ALE to read pulse delay time

Read pulse (falling edge)

to data bus delay time

Data hold time

Write cycle timings (Fig. 4)

ALE to write pulse delay time

Address set up time to \overline{WR} Data set up time before \overline{WR} Data hold time after \overline{WR}

PORT A

Associated register: R6 — bits 0 to 4 — read/write

Associated pins: PA0 to PA4.

Operation

This is a 5-bit general purpose input/output port. The outputs are latched and are open drain up to nominal 12 V.

The latches may be accessed by the microprocessor via BUS D0 to D7 by a read or write sequence to register R6. If any pin of the port is used as an input then its output latch must first be written with a '1'. This allows the external circuit to control the pin. The state of the pins may be read by the microprocessor by reading R6. If the supply to the open drain outputs is turned off before the VDD supply to the IC, then the PORT must first be cleared by writing 1's to the output latch before operation.

PORT A might typically be used in viewdata mode as an interface to a non-volatile memory in which telephone and password numbers may be stored.

PORT B

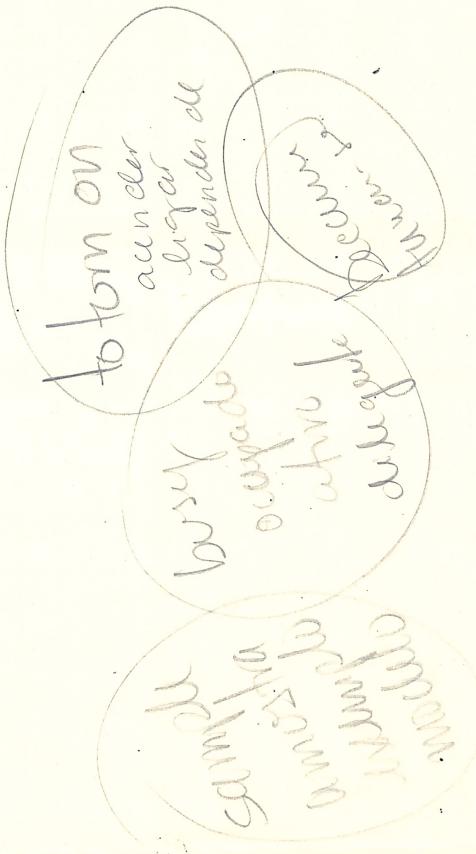
Associated register: R7 — bits 0 to 3 — read/write

Associated pins: PB0 to PB3

Operation

This is a 4-bit general purpose input/output port. It behaves in exactly the same way as PORT A except that access is by addressing R7, and that outputs PB1 to PB3 are open drain to nominal 5 V. PB0 is open drain to nominal 12 V, and might typically be used in combined teletext/viewdata applications to control the Picture On function.

DEVELOPMENT SAMPLE DATA



min.

typ.

max.

V_{IL}

-0.3

-

0.6

V

V_{IH}

2.2

-

5.5

V

 I_{IR}

-

-

10

 μA C_1

-

-

7

pF

 t_{DS}

3

-

-

 μs t_{DH}

3

-

-

 μs t_{CH}

4

-

-

 μs t_{CL}

4

-

62

 μs t_{BC}

140

-

 ∞ μs f_{DLIM}

16

-

160

kHz

 t_{ALEH}

400

-

-

ns

 t_{ALE}

-

2500

-

ns

 t_{WL}

-

-

700

-

ns

 t_{LA}

80

-

-

ns

 t_{AL}

120

-

-

ns

 t_{ALR}

80

-

-

ns

 t_{RD}

-

-

500

ns

 t_{DR}

0

-

200

ns

 t_{ALW}

80

-

-

ns

 t_{AW}

230

-

-

ns

 t_{DW}

500

-

-

ns

 t_{WD}

120

-

-

ns

Transmitter B is initiated by writing two bytes to the transmit holding register (R11). This sets IBTXRDY to '0'. The DLIM line is sampled to detect the line busy state, and when the line is free a time out starts.

If further DLIM's are detected before the end of the time out period the time out is reset and the sequence will begin again. When the time out has been completed the contents of the holding register are transferred to the output shift register and word length counter. The data and correct number of data clocks are then transmitted, at the completion of which IBTXRDY is returned to a '1'. New data should not be written to the transmit holding register (R11) while IBTXRDY = '0'. If the line is busy when a transmission is requested, the transmission will not start until 300 - 330 μ s after the line becomes free (last DLIM).

Receiver B may operate either as a two line receiver with DATA and DLIM, or as a three line DATA, DLEN and CLK receiver. DLIM ANDLIM A use the same pin, the function of which is selected by the DLEN ANDLIM A command DO, register R3 (command). The 62.5 kHz clock (pin 18 CLK) may be used either as an input for receiver A (as described above), or to synchronise transmitter B outputs, or as an output synchronous with transmitter B. The function is selected by CLOCK IN/OUT command D1 in R3.

Fig. 3 Read cycle timing

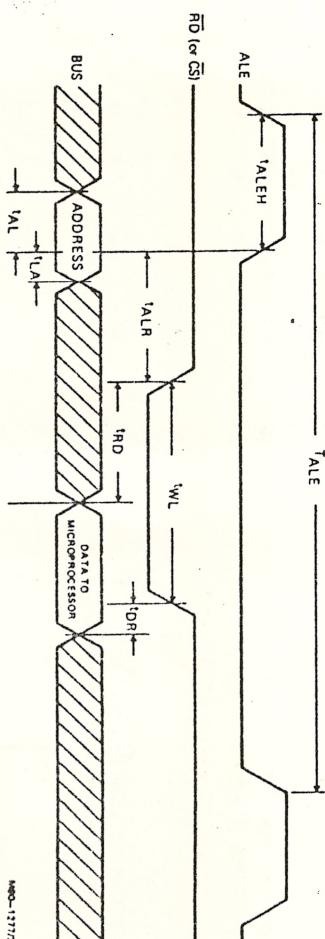


Fig. 3 Read cycle timing

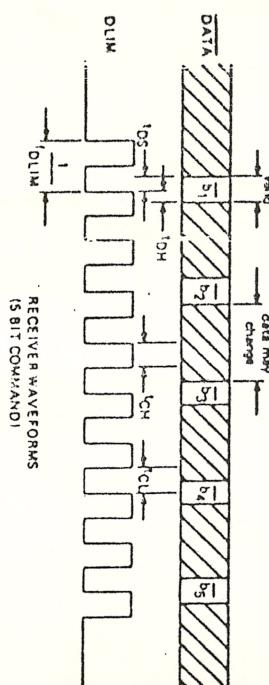


Fig. 4 Development Sample Data

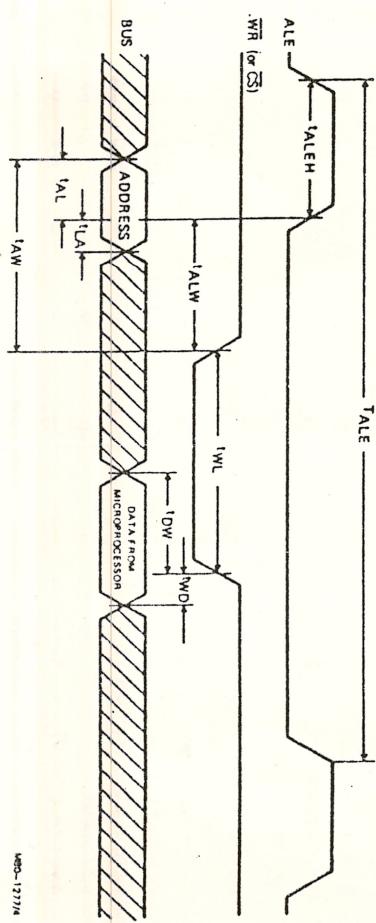


Fig. 4 Write cycle timing

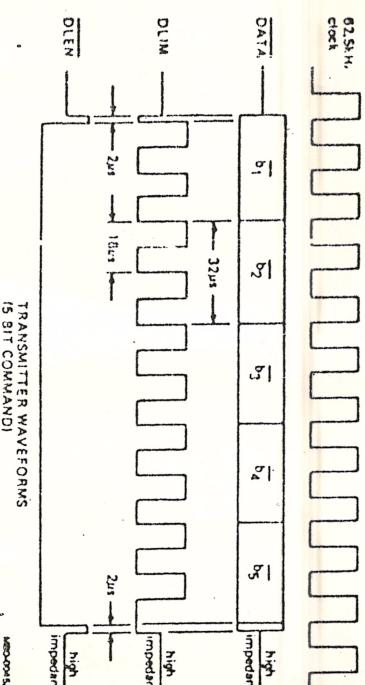


Fig. 14 IBUS waveforms

Inputs/Outputs

These are protected against connection to V_{SS} or V_{DD}

DATA A, DLIM B, DLIN B, IBCLK B, IBRXRDY B

Input voltage; LOW

Input voltage; HIGH

Input leakage current ($V_I = 0$ to 5.5 V)
(3 state buffers off)

Input capacitance

Output voltage; LOW ($I_{OL} = 1.6$ mA)

Output voltage; HIGH ($-I_{OH} = 200$ μ A)

Output rise and fall times ($C_L = 300$ pF)

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_r = 1$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 1$ μ s

other timings as IBUS A

DOCDI (open drain output)

Input voltage; LOW

Input voltage; HIGH

Input leakage current ($V_I = 0$ to 5.5 V)
(output transistor off)

Input capacitance

Output voltage; LOW ($I_{OL} = 1.6$ mA)

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_r = 0.4$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 0.4$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 7$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 7$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

$V_{IL} = -0.3$ μ A
 $V_{IH} = 2.0$ μ A
 $t_f = 3$ μ s

$V_{IL} = 0.8$ μ A
 $V_{IH} = 5.5$ μ A
 $t_f = 3$ μ s

$V_{IL} = -0.4$ μ A
 $V_{IH} = 10$ μ A
 $t_f = 40$ μ F

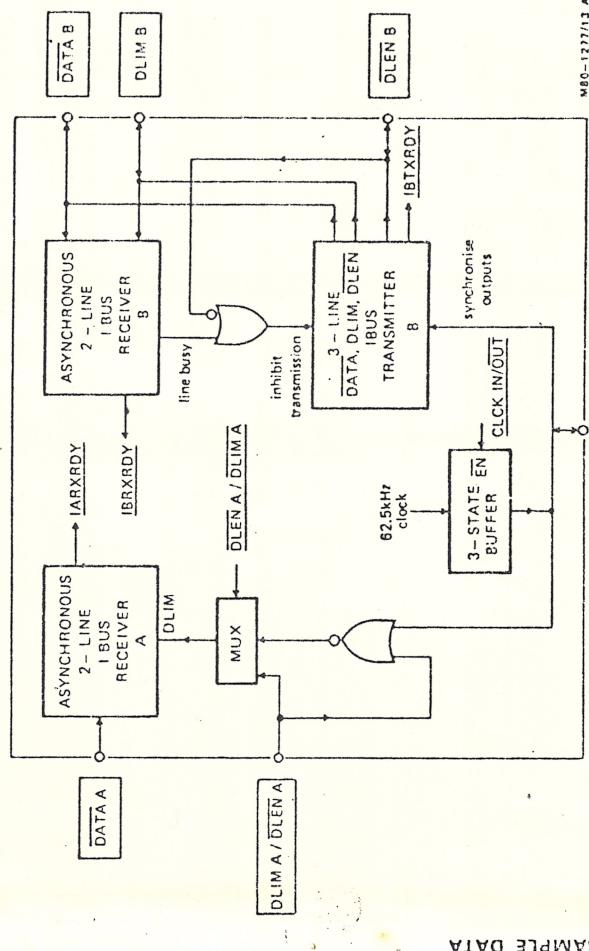


Fig.13 IBUS block diagram

For the transmitter the register pair is organised as:

1st byte	D7	D6	D5	D4	D3	D2	D1	D0
TXB – R11A	8	7	6	5	4	3	2	1
2nd byte	D7	D6	D5	D4	D3	D2	D1	D0

(B – R11B Word length MSB Word length LSB)

Where 1, 2, etc. means first data bit transmitted, second data bit transmitted, etc.

IARXRDY or IBRXRDY (D1 in status registers R1 and R0) are set when a message has been received by RXA or RXB respectively. These flags also inhibit the receive holding registers from being overwritten by subsequent messages until the holding registers have been read. Reading a holding register pair will reset the relevant IARXRDY or IBRXRDY flags.

IBUS A receiver and IBUS B receiver/transmitter (see Fig.13)

Inputs/Outputs (continued)

min. typ. max.

PBO (PORT B) (open drain output) as PORT A except

V_{OL} - - - 0.4 V

Output voltage; LOW ($|I_{OL}| = 1.6 \text{ mA}$)

V_{OH} - - -

Output voltage; HIGH

C_L - - -

Load capacitance

13.2 V

PB1 to PB3 (PORT B)

100 pF

Input voltage; LOW

V_{IL} - - -

Input voltage; HIGH

V_{IH} 2.0 - - 5.5 V

Input capacitance

C_I - - -

Load capacitance

C_L - - - 100 pF

Output voltage; LOW ($|I_{OL}| = 1.6 \text{ mA}$)

V_{OL} - - -

Off state leakage current ($V_I = 0$ to 5.5 V)

I_{OL} - - -

Output voltage; LOW ($|I_{OL}| = 1.6 \text{ mA}$)

V_{IL} - - -

Input voltage; HIGH

V_{IH} 2.0 - - 5.5 V

Output voltage; LOW ($|I_{OL}| = 1.6 \text{ mA}$)

V_{OL} - - -

Output voltage; HIGH ($-|I_{OH}| = 200 \mu\text{A}$)

V_{OH} 2.4 - - V

Input leakage current ($V_I = 0$ to 5.5 V)

I_{IR} - - -

(3-state buffers off)

C_I - - -

Input capacitance

t_r - - -

Output rise and fall times ($C_L = 150 \text{ pF}$)

t_f - - -

Output fall time

t_f - - -

Output rise time

t_r - - -

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output voltage; LOW ($|I_{OL}| = 50 \mu\text{A}$)

V_{OH} 2.4 - - V

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OL} 2.4 - -

Output voltage; HIGH ($-|I_{OH}| = 200 \mu\text{A}$)

V_{OH} 2.4 - - V

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

Output voltage; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

V_{OL} - - -

Output current; HIGH ($V_{OH} = 0.8 \text{ V}$ clamped)*

I_{OH} 200 - - 2000 μA

*These outputs are normally intended to drive the base-emitter junction of a bipolar transistor and so in normal use the V_{OH} may be clamped to V_{be}.

RESET FUNCTION

It is possible to reset the SAA5070 to its nominal state either automatically on power-on by means of an internal power-on reset circuit, or by setting D5 in command register (R3) to '1', which returns to '0' on completion of the reset sequence. The device resets to viewdata mode, i.e. 75 baud transmit rate, even parity, etc., as shown by the all zero's state in registers R0 to R3, R5, R7 and R8 except for LTXRDY, BTXRDY and TTXRDY (in the status registers R0 and R1) which will come up as '1' after the transmitters have been reset, showing that they are ready to accept new data.

RXA - R10A	L - 4	L - 5	L - 6	L - 7	L - 8	L - 9	L - 10	L - 11
RXB - R11A	D7	D6	D5	D4	D3	D2	D1	D0

2nd byte

Word length	Word length	Word length	Word length	LSB	L	L - 1	L - 2	L - 3
RXA - R10B	Word length	Word length	Word length	L	L - 1	L - 2	L - 3	

Word length

Where L, L - 1 etc. means last data bit received, last minus one etc.

APPLICATION DATA

Chip organisation
 Each section of the SAA5070 may be accessed by the microprocessor via a register (of up to 8-bits) connected to an internal data bus. There are 15 registers on chip accessed by 11 addresses. Some of the registers are two-level i.e. two bytes of data are transferred by two successive read (or write) sequences to the same address, also some read only registers have the same address as a write only register.

An appendix lists the registers, their contents, and their use.

Section descriptions

The description of each section includes associated registers, flags, and pins, as well as the method of operation. On the following block diagrams external pins are shown boxed and internal flags are shown underlined.

Microprocessor Interfaces	
DO to D7	I/O
Associated pins:	ALE
WR	input address latch enable from microprocessor
RD	input write pulse from microprocessor
CS	input read pulse from microprocessor
	input chip select:

Operation

The control microprocessor communicates with the SAA5070 via an 8-bit data I/O port D0 to D7. An internal read or write pulse is produced by gating RD and WR with CS. A single register is enabled onto the internal bus by gating the read or write lines with the address decoder outputs. The register address is taken from the 4 least significant data bits latched on the falling edge of ALE. (See timing diagrams Figs. 3, 4). The address (D3 most significant, D0 least significant) relates directly to the register numbers shown in the register map, detailed in the appendix, and referred to in other section descriptions.

The control microprocessor communicates with the SAA5070 via an 8-bit data I/O port D0 to D7. An internal read or write pulse is produced by gating RD and WR with CS. A single register is enabled onto the internal bus by gating the read or write lines with the address decoder outputs. The register address is taken from the 4 least significant data bits latched on the falling edge of ALE. (See timing diagrams Figs. 3, 4). The address (D3 most significant, D0 least significant) relates directly to the register numbers shown in the register map, detailed in the appendix, and referred to in other section descriptions.

Four registers not specifically related to any one section are included. These are the status registers R0 and R1, the mode register R2, and the command register R3. These registers are used to determine the current status of the device, to dictate the mode of operation or to initiate a specific operation. The status registers are read only, the mode and command registers are read/write. When writing to these registers, it is recommended that the unallocated bits are set to '0'. On reading the registers the state of the unallocated bits should be assumed to be random. The exact functions of the flags contained in these registers are described in the section description to which they relate.

Autodial section (see Fig. 5)

Associated Register:	--	R8	--	D0 to D3 write only
Associated pins:	D0	D1	D2	D4, D7 read/write

Associated flags in other registers:	None
Associated pins:	D0, D1 output D2, D3 output

to drive dialling relays

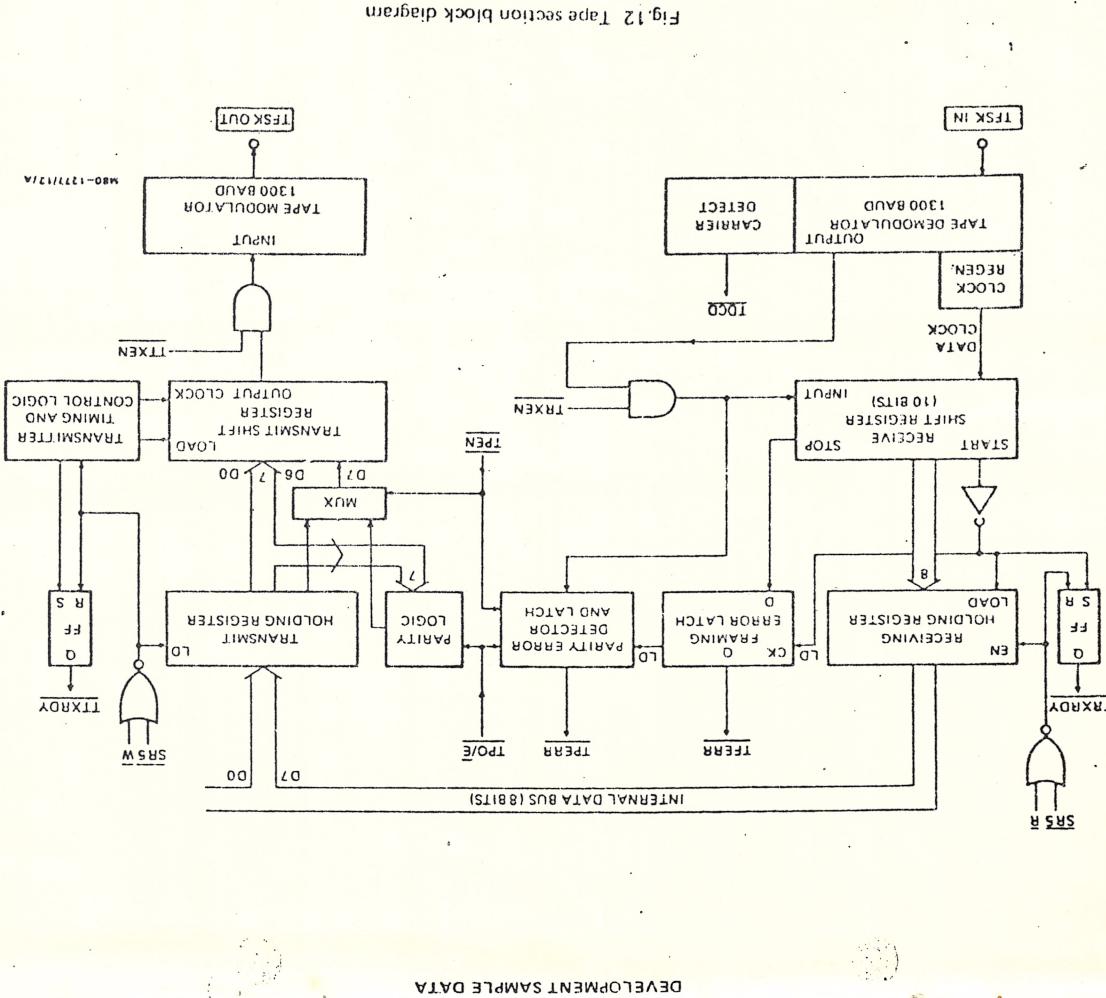


Fig. 12 Tape section block diagram